

Title (en)

POLYESTER-POLYCARBONATE COMPOSITION WITH IMPROVED HOT-PLATE WELDABILITY

Title (de)

POLYESTER-POLYCARBONAT-MISCHUNG MIT VERBESSERTER VERSCHWEISSBARKEIT MITTELS EINER HEIZPLATTE

Title (fr)

COMPOSITION POLYESTER-POLYCARBONATE A SOUDABILITE PAR PLAQUE CHAUFFANTE AMELIOREE

Publication

**EP 1115790 A1 20010718 (EN)**

Application

**EP 00946995 A 20000630**

Priority

- JP 18943599 A 19990702
- US 0018294 W 20000630

Abstract (en)

[origin: WO0102487A1] The object of the present invention is to provide a resin composition with improved hot-plate weldability, in which no carbonized resin remains on the hot plate, and in which there is no drawing out of fine filaments of the resin. The present invention provides a resin composition which contains (A) a polyester resin at the rate of 98 to 1 wt %; (B) a polycarbonate resin at the rate of 1 to 98 wt %; (C) a core-shell copolymer at the rate of 0.5 to 18 wt %, and (D) a polytetrafluoroethylene with a number average molecular weight of 30,000 or greater at the rate of 0.01 to 4 wt % (with the total of (A) through (D) being 100 wt %).

IPC 1-7

**C08L 67/00**; **C08L 69/00**

IPC 8 full level

**C08L 67/00** (2006.01); **B29C 65/00** (2006.01); **B29C 65/20** (2006.01); **C08L 67/02** (2006.01); **C08L 69/00** (2006.01); **C08L 27/18** (2006.01); **C08L 51/04** (2006.01)

CPC (source: EP KR)

**B29C 65/20** (2013.01 - EP KR); **B29C 66/71** (2013.01 - EP KR); **C08L 27/18** (2013.01 - KR); **C08L 51/04** (2013.01 - KR); **C08L 67/02** (2013.01 - EP KR); **C08L 69/00** (2013.01 - EP KR); **B29K 2067/00** (2013.01 - EP); **B29K 2069/00** (2013.01 - EP); **B29L 2031/30** (2013.01 - EP); **B29L 2031/747** (2013.01 - EP); **C08J 2300/22** (2013.01 - KR); **C08L 27/18** (2013.01 - EP); **C08L 51/04** (2013.01 - EP); **C08L 2207/53** (2013.01 - KR); **C08L 2666/02** (2013.01 - KR)

Citation (search report)

See references of WO 0102487A1

Designated contracting state (EPC)

DE ES FR GB NL

DOCDB simple family (publication)

**WO 0102487 A1 20010111**; CN 1321180 A 20011107; EP 1115790 A1 20010718; JP 2001011293 A 20010116; JP 4486180 B2 20100623; KR 20010073015 A 20010731

DOCDB simple family (application)

**US 0018294 W 20000630**; CN 00801902 A 20000630; EP 00946995 A 20000630; JP 18943599 A 19990702; KR 20017002487 A 20010227